CONTROL CIRCUIT FOR SMPS

The TDA2581 is a monolithic integrated circuit for controlling switched-mode power supplies (SMPS) which are provided with the drive for the horizontal deflection stage.

The circuit features the following:

- Voltage controlled horizontal oscillator.
- Phase detector.
- Duty factor control for the positive-going transient of the output signal.
- Duty factor increases from zero to its normal operation value.
- Adjustable maximum duty factor.
- Over-voltage and over-current protection with automatic re-start after switch-off.
- Counting circuit for permanent switch-off when n-times over-current or over-voltage is sensed.
- Protection for open-reference voltage.
- Protection for too low supply voltage.
- Protection against loop faults.
- Positive tracking of duty factor and feedback voltage when the feedback voltage is smaller than the reference voltage minus 1,5 V.

QUICK REFERENCE DATA

Supply voltage	V ₉₋₁₆	typ.	12	V .
Supply current	lg	typ.	15	mΑ
Input signals				
Horizontal drive pulse (peak-to-peak value)	V _{3-16(p-p)}	typ.	11	٧
Flyback pulse (differentiated deflection current); peak-to-peak value External reference voltage	V ₂₋₁₆ (p-p) V ₁₀₋₁₆	typ. typ.	5 6,7	V V
Output signals Duty factor of output pulse	δ	> < 98	0 ± 0,6	% %
Output voltage at I _O < 20 mA (peak value) Output current (peak value)	V ₁₁₋₁₆ M I ₁₁ M	typ.	11,8 40	V mA

PACKAGE OUTLINES

TDA2581: 16-lead DIL; plastic (SOT-38). TDA2581Q: 16-lead QIL; plastic (SOT-58).

RATINGS				
Limiting values in accordance with the Absolute Max	imum Systen	n (IEC 134	4)	
Supply voltage	V ₉₋₁₆	max.	14	
Voltage at pin 11	V11-16		0 to 14	٧
Output current	111	max.	40	
Total power dissipation	P _{tot}	max.	340	
Storage temperature	T _{stg}		-25 to +125	
Operating ambient temperature	T _{amb}		-25 to +80	оС
CHARACTERISTICS				
$V_{9-16} = 12 \text{ V}; V_{10-16} = 6,7 \text{ V}; T_{amb} = 25 ^{\circ}\text{C}; \text{ measure}$	ured in the ci	rcuit on p	age 2	
Supply voltage range	V ₉₋₁₆	typ.	12 10 to 14	
Protection voltage too low supply voltage	V ₉₋₁₆	typ.	9,4 8,6 to 9,9	
Supply current at $\delta = 50\%$	lg	typ.	15	mΑ
Supply current during protection	lg .	typ.	15	mA
Minimum required supply current	lg	<	18,5	mA*
Power consumption	P	typ.	180	mW
Required input signals				
Reference voltage	V ₁₀₋₁₆	typ.	6,7 5,6 to 7,5	
High reference voltage protection: threshold voltage	V ₁₀₋₁₆	typ.	8,4 7,9 to 8,9	
Feedback input impedance at pin 8	^Z 8-16	typ.	200	kΩ
Horizontal drive pulse (square-wave or differentiated; negative transient is reference) peak-to-peak value	V _{3-16(p-p)}	typ.	11 5 to 12	
Flyback pulse or differential deflection current	V ₂₋₁₆	et e.g. North	1 to 5	v.
Over-current protection: threshold voltage	-V ₆₋₁₆	typ.	640 690 to 695	
	+V ₆₋₁₆	typ.	680 640 to 735	mV mV.▲
Over-voltage protection: threshold voltage	V7-16	typ. V10-16	V ₁₀₋₁₆ -60 -130 to V ₁₀₋₁₆ -0	
	7			

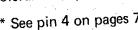
^{*} This value refers to the minimum required supply current that will start all devices under the

following conditions: $V_{9-16} = 10 \text{ V}$; $V_{10-16} = 6.8 \text{ V}$; $\delta = 50\%$.

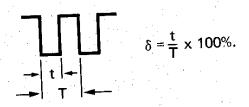
** Voltage obtained via an external reference diode. Specified voltages do not refer to the nominal voltages of reference diodes.

[▲] This spread is inclusive temperature rise of the IC due to warming up. For other ambient temperatures the values must be corrected by using a temperature coefficient of typical -1,85 mV/°C.

CHARACTERISTICS (continued) Remote control voltage; switch off switch on	V4-16 V4-16	> <	5,8 V* 4,5 V*
System of the second of the se			
Delivered output signals			
Horizontal drive pulse (loaded with a resistor of 560 Ω to +12 V) peak-to-peak value	V ₁₁₋ 16(p-p) I _{11M}	> <	11,6 V 40 mA
Output current; peak value		typ	200 mV
Saturation voltage of output transistor at I ₁₁ = 20 mA	V _{CEsat}	<	400 mV
at 111 = 40 mA	V _{CEsat}	< >	525 mV 0 %
Duty factor of output pulse**	δ	< 98	± 0,6 %
Duty lactor of output pass	14	-71	120 μΑ
Charge current for capacitor on pin 4	15	-71-	130 μΑ
Charge current for capacitor on pin 5	¹ 10	T	1 mA 1,45 mA
Supply current for reference	10	υ,ο ιο	
Oscillator Temperature coefficient		typ.	-300 ppm/°C -400 ppm/°C
		typ,	-1,5 %
Relative frequency deviation for V10-16 changing from 6 to 7 V		€	-2 %
Oscillator frequency spread (with fixed		€	±3 %
external components)		typ.	4,5 kHz/V
Frequency control sensitivity at pin 15			and the second of the second o
Phase control loop		typ.	5 kHz/μs
Loop gain of APC-system (automatic phase control)	Δf	typ.	±1,5 kHz
Catching range	Δ.		
Phase relation between negative transient of	t	typ.	
sync pulse and middle of Tryback	Δt	€	±0,4 μs
Tolerance of phase relation			



^{*} See pin 4 on pages 7 and 8.* The duty factor is specified as follows:



The maximum duty factor value can be set to a desired value (see application information pin 12 (page 9).

For component values see circuit diagram on page 2.

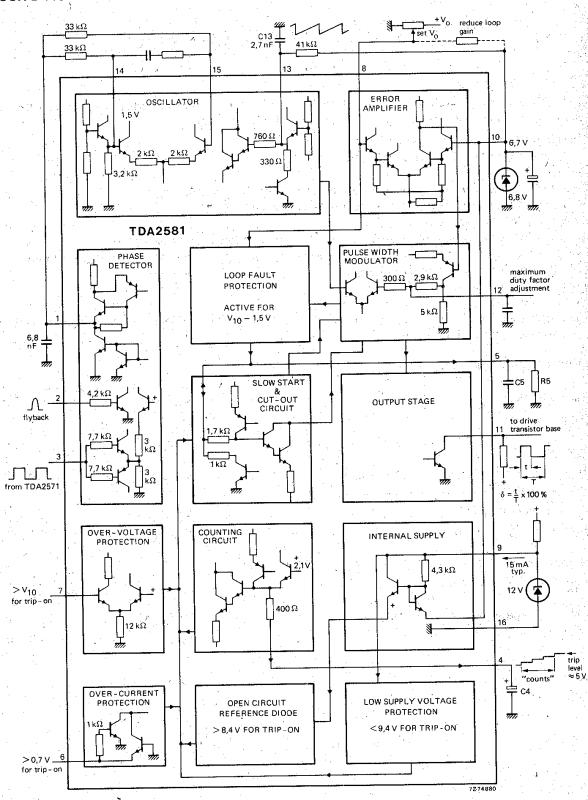


PINNING

- 1. Phase detector output
- 2. Flyback pulse position input
- 3. Reference frequency input
- 4. Re-start count capacitor/remote control input
- 5. Slow start and transfer characteristic for low feedback voltages
- 6. Over-current protection input
- 7. Over-voltage protection input
- 8. Feedback voltage input

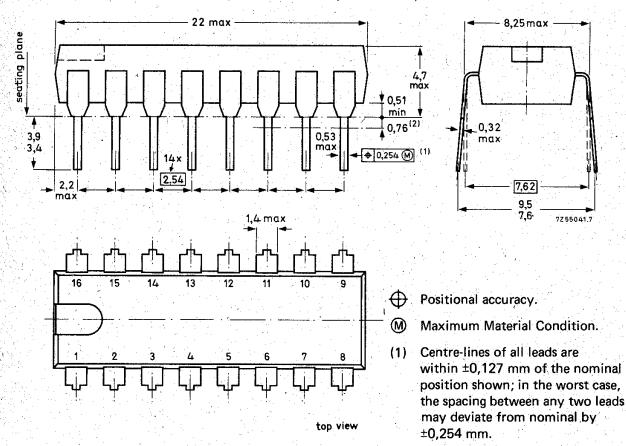
- 9. Positive supply
- 10. Reference input
- 11. Output
- 12. Maximum duty factor adjustment/smoothing
- 13. Oscillator timing network
- 14. Reactance stage reference voltage
- 15. Reactance stage input
- 16. Negative supply (ground)

BLOCK DIAGRAM



Note: trip levels are nominal values.

16-LEAD DUAL IN-LINE; PLASTIC (SOT-38)



Dimensions in mm

(2) Lead spacing tolerances apply from seating plane to the line indicated.

SOLDERING

1. By hand

Apply the soldering iron below the seating plane (or not more than 2 mm above it). If its temperature is below 300 °C it must not be in contact for more than 10 seconds; if between 300 °C and 400 °C, for not more than 5 seconds.

2. By dip or wave

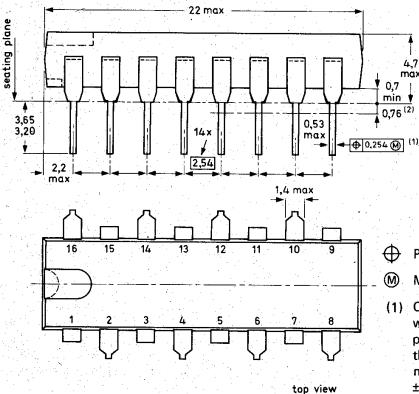
The maximum permissible temperature of the solder is 260 °C; this temperature must not be in contact with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified storage maximum. If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

3. Repairing soldered joints

The same precautions and limits apply as in (1) above.

16-LEAD QUADRUPLE IN-LINE; PLASTIC (SOT-58)



Dimensions in mm

- 8,25 max 5,08 10,16 7255830.3
- Positional accuracy.

max 0,7

- (M) Maximum Material Condition.
- (1) Centre-lines of all leads are within ±0,127 mm of the nominal position shown; in the worst case, the spacing between any two leads may deviate from nominal by ±0,254 mm.
- Lead spacing tolerances apply from seating plane to the line indicated.

SOLDERING

1. By hand

Apply the soldering iron below the seating plane (or not more than 2 mm above it). If its temperature is below 300 °C it must not be in contact for more than 10 seconds; if between 300 °C and 400 °C, for not more than 5 seconds.

2. By dip or wave

The maximum permissible temperature of the solder is 260 °C; this temperature must not be in contact with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified storage maximum. If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

3. Repairing soldered joints

The same precautions and limits apply as in (1) above.